# 2SC3931

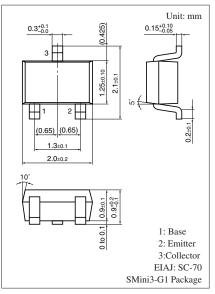
### Silicon NPN epitaxial planar type

For high-frequency amplification

### Features

- Optimum for RF amplification of FM/AM radios
- $\bullet$  High transition frequency  $f_{\rm T}$
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$ Parameter Symbol Unit Rating Collector-base voltage (Emitter open) 30 V V<sub>CBO</sub> Collector-emitter voltage (Base open) V<sub>CEO</sub> 20 V 3 V Emitter-base voltage (Collector open) V<sub>EBO</sub> 15 Collector current $I_C$ mА Collector power dissipation 150 mW $\mathbf{P}_{\mathbf{C}}$ T<sub>j</sub> 150 °C Junction temperature °C Storage temperature T<sub>stg</sub> -55 to +150



#### Marking Symbol: U

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

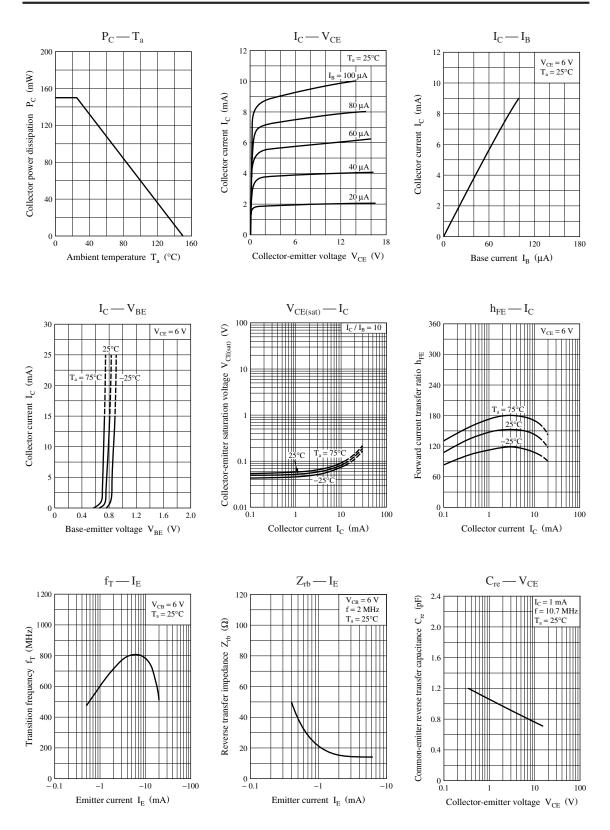
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{C} = 10 \ \mu A, \ I_{E} = 0$	30			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_E = 10 \ \mu A, \ I_C = 0$	3			V
Base-emitter voltage	V <sub>BE</sub>	$V_{CB} = 6 V, I_E = -1 mA$		720		mV
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CB} = 6 V, I_E = -1 mA$	65		260	
Transition frequency	f <sub>T</sub>	$V_{CB} = 6 V, I_E = -1 mA, f = 200 MHz$	450	650		MHz
Common-emitter reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 6 V, I_E = -1 mA, f = 10.7 MHz$		0.8	1.0	pF
Power gain	G <sub>P</sub>	$V_{CB} = 6 V, I_E = -1 mA, f = 100 MHz$		24		dB
Noise figure	NF	$V_{CB} = 6 V, I_E = -1 mA, f = 100 MHz$		3.3		dB

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

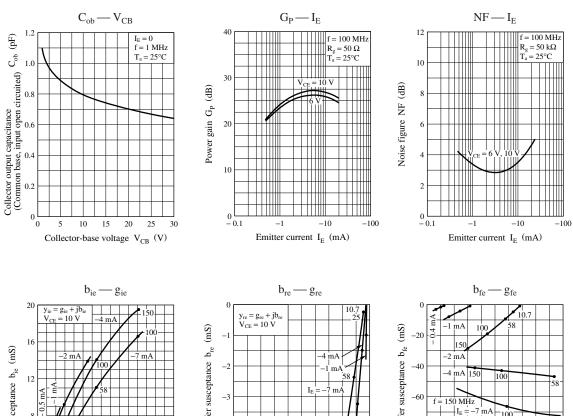
#### 2. \*: Rank classification

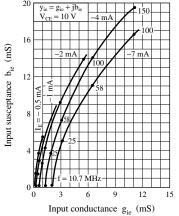
Rank	С	D
$h_{\rm FE}$	65 to 160	100 to 260

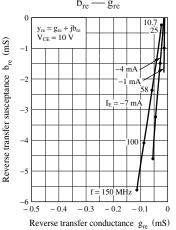
### Panasonic

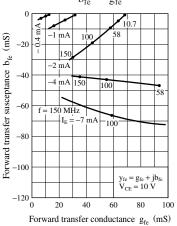


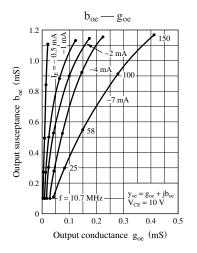
### **Panasonic**











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